

J. Number	Hits	Search Text	DB	Time stamp
1	0	hiroki-tsutomu.in.	USPAT;	2003/11/10 12:20
2	4	hiroki-tsutomu.in.	US-PGPUB	2003/11/10 12:21
3	4	hiroki-tsutomu.in.	USPAT;	2003/11/10 12:21
4	0	hiroki-tsutomu\$.in.	US-PGPUB	2003/11/10 12:22
5	2115	((414/935) or (414/939) or (118/719) or (156/345.31) or (156/345.32)).CCFS.	USPAT;	2003/11/10 12:22
6	0	("5and@pd>-20030101").PN.	US-PGPUB	2003/11/10 12:24
7	86	((414/935) or (414/939) or (118/719) or (156/345.31) or (156/345.32)).CCFS.) and @pd>-20030701	USPAT;	2003/11/10 12:24
-	116	(414/\$.cccls. 118/\$.cccls. 156/345.\$.\$cccls.) and (articulat\$3 with linear\$3)	USPAT;	2003/07/28 08:27
-	54	(arm hand robot) with (articulat\$3 with linear\$3 with extend\$3)	US-PGPUB	2003/07/27 19:29
-	1	("5993141").PN.	US-PGPUB	2003/07/28 08:23
-	5	5993141.URPN.	USPAT	2003/07/28 08:23
-	28	("4009785" "4410209" "4566726" "4602627" "4775281" "4875824" "5090549" "5100502" "5147175" "5286296" "5382128" "5439547" "5474410" "5479108" "5562387" "5636963" "5647626" "5647724" "5669644" "5697745" "5755469" "5789878" "5900105" "5950495" "5993141" "6048162" "6073366" "6224319").PN.	USPAT	2003/07/27 19:30
-	5	5993141.URPN.	USPAT	2003/07/28 08:23
-	5	5993141.URPN.	USPAT	2003/07/28 08:23
-	221	(414/\$.cccls. 118/\$.cccls. 156/345.\$.\$cccls.) and (articulat\$3 same linear\$3)	USPAT;	2003/07/28 08:25
-	151	(414/\$.cccls. 118/\$.cccls. 156/345.\$.\$cccls.) and (articulat\$3 same linear\$3 same (hand robot arm effector blade))	US-PGPUB	2003/07/28 08:28
-	116	(414/\$.cccls. 118/\$.cccls. 156/345.\$.\$cccls.) and (articulat\$3 with linear\$3)	USPAT;	2003/07/28 08:27
-	68	((414/\$.cccls. 118/\$.cccls. 156/345.\$.\$cccls.) and (articulat\$3 same linear\$3 same (hand robot arm effector blade))) not ((414/\$.cccls. 118/\$.cccls. 156/345.\$.\$cccls.) and (articulat\$3 with linear\$3))	US-PGPUB	2003/07/28 08:27
-	0	(c23c0165.ipc.) and (articulat\$3 same linear\$3 same (hand robot arm effector blade))	EPO; JPO; DERWENT	2003/07/28 08:31
-	0	(c23c0165.ipc.) and (articulat\$3 same linear\$3 same (hand robot arm effector blade))	EPO; JPO; DERWENT	2003/07/28 08:29
-	10	(c23c0165.ipc.) and (linear\$3 same (hand robot arm effector blade))	EPO; JPO; DERWENT	2003/07/28 08:29
-	213	(articulat\$3 same linear\$3 same (hand robot arm effector blade))	EPO; JPO; DERWENT	2003/07/28 08:31
-	3	(articulat\$3 same linear\$3 same (hand robot arm effector blade) same (wafer substrate semiconductor))	EPO; JPO; DERWENT	2003/07/28 08:40
-	70	((reciprocate\$5 extend\$3 retract\$4) same linear\$3 same (hand robot arm effector blade) same (wafer substrate semiconductor))	EPO; JPO; DERWENT	2003/07/28 08:41
-	654	((reciprocate\$5 extend\$3 retract\$4) same linear\$3 same (hand robot arm effector blade) same (wafer substrate semiconductor))	USPAT;	2003/07/28 09:01
-	70	((reciprocate\$5 extend\$3 retract\$4) same linear\$3 same (hand robot arm effector blade) same (wafer substrate semiconductor))	EPO; JPO; DERWENT	2003/07/28 08:41

172	{{reciprocate\$5 extend\$3 retract\$4} with linear\$3 with (hand robot arm effector blade) same (water substrate semiconductor))	USPAT; US-PGPUB	2003/07/28 09:52
25	4907931.URPN.	USPAT	2003/07/28 09:21
9	("3503527" "4103232" "4407627" "4441803" "4457664" "4655584" "4695215" "4746256" "4752898").PN.	USPAT	2003/07/28 10:37
25	4695215.URPN.	USPAT	2003/07/28 09:26
13	((("4552504") or ("4654106") or ("4908095") or ("5011366") or ("5064340") or ("5306380") or ("5655060") or ("5746565") or ("5823736") or ("5989346") or ("6051101") or ("6155768") or ("6164894")).PN.	USPAT; USPAT; US-PGPUB	2003/07/28 10:47
11	5306380.URPN.	USPAT	2003/07/28 09:55
13	5823736.URPN.	USPAT	2003/07/28 10:40
8	("3817402" "4591044" "4776745" "5197089" "5345639" "5374147" "5445491" "5540535").PN.	USPAT	2003/07/28 10:42
29	414/609.ccls. and (wafer semiconductor substrate)	USPAT; US-PGPUB	2003/07/28 10:58
0	6331095.URPN.	USPAT	2003/07/28 10:54
7	("4816098" "5823736" "5879128" "5879460" "589301" "5934856" "5989346").PN.	USPAT	2003/07/28 10:54
0	414/222.04.ccls. and (wafer semiconductor substrate)	USPAT; US-PGPUB	2003/07/28 10:59
21	414/222.04.ccls. and (wafer semiconductor substrate)	USPAT; US-PGPUB	2003/07/28 10:59
1	414/222.05.ccls. and (wafer semiconductor substrate)	USPAT; US-PGPUB	2003/07/28 11:00
8	414/222.06.ccls. and (wafer semiconductor substrate)	USPAT; US-PGPUB	2003/07/28 11:00
34	(414/222.04.ccls. and (wafer semiconductor substrate)) (414/222.05.ccls. and (wafer semiconductor substrate)) (414/222.06.ccls. and (wafer semiconductor substrate))	USPAT; US-PGPUB	2003/07/28 11:00